Sir:

Transmitted herewith for filing is the Patent Application of:

Inventor: HONG YU YU, MING-FU LI, DIM-LEE KWONG, LAKSHMI KANTA BERA

For:

A THERMAL ROBUST SEMICONDUCTOR DEVICE USING HFN AS METAL GATE ELECTRODE AND THE

MANUFACTURING PROCESS THEREOF

Enclosed are:					
X 4 sheets of drawing(s) - formal.					
X An assignment of the invention to National University of Singapore and Agency For Science, Technology and Research					
An associate	power of attorney	Applicant claims	small entity status		
Request & C	ertification under 35 US	C 122(b)(2)(b)(i)			
The filing fee has been	calculated as shown bel	ow:			
C	(Col. 1) (Col. 2)		OTHER THAN A SMALL ENTITY		
FOR:	NO. FILED	NO. EXTRA	RATE	FEE	
BASIC FEE		><		\$ 770.	
TOTAL CLAIMS	34 -20=	14	x 18 =	\$ 252.	
INDEP CLAIMS	4 -3=	1	x 86 =	\$ 86.	
		_	SUB TOTAL	\$ 1,108.	
			ASSIGNMENT	\$40.	
			TOTAL	\$ 1.148.	
Please charge my Deposit Account No. 19-0033 in the amount of \$ 1,148. A duplicate copy of this sheet is enclosed. The Commissioner is hereby authorized to charge payment of the following fees associated with this communication or credit any					
The Commissioner is hereby authorized to charge payment of the following fees associated with this communication or credit any					
overpayment to Deposit Account No. 19-0033. A duplicate copy of this sheet is enclosed.					
X Any additional filing fees required under 37 CFR §1.16.					
X Any patent application processing fees under 37 CFR §1.17.					
Respectfully submitted,					
STEPHEN B. ACKERMAN, REG. NO. 37,761					

EXPRESS MAIL CERTIFICATE

Express Mail No.EV319114250US

I hereby certify that this correspondence is being deposited with the United States Postal Service as Express Mail in an envelope addressed to Commissioner for Patents, P.O. Box 1450, Alexandria, VA, 22313-1450. Applicant and/or Attorney requests the date of deposit as the Filing Date.

Date of deposit